December 14, 2017

Invensas Completes DBI Technology Transfer to Teledyne DALSA

One of the world's largest independent MEMS foundries ready to manufacture MEMS and image sensor products utilizing Invensas wafer bonding and 3D interconnect technology

SAN JOSE, Calif.--(BUSINESS WIRE)-- Invensas, a wholly owned subsidiary of Xperi Corporation ("Xperi") (NASDAQ:XPER), today announced the successful technology transfer of its Direct Bond Interconnect (DBI®) to Teledyne DALSA, a Teledyne Technologies company. This capability enables Teledyne DALSA to deliver next-generation MEMS and image sensor solutions that are more compact and higher performance to customers in the automotive, IoT and consumer electronics markets. Teledyne DALSA is an international leader in high performance digital imaging and semiconductors and one of the world's foremost pure-play MEMS foundries. Invensas and Teledyne DALSA announced the signing of a development license in February 2017.

"In partnership with Invensas, we have successfully completed the transfer of its revolutionary DBI technology to our manufacturing facilities in Bromont," said Edwin Roks, president of Teledyne DALSA. "We are now ready to offer this enabling platform as part of our foundry services to customers, including our own business lines, seeking smaller, higher performance and more reliable MEMS and imaging solutions."

"The manufacturing team at Teledyne DALSA has done a fantastic job bringing up our DBI process and is well-positioned to enable a new generation of high performance MEMS and image sensor solutions," said Craig Mitchell, president of Invensas. "We are excited about the prospects for DBI to be integrated into a wide range of Teledyne DALSA's branded products as well as those of their foundry customers."

DBI technology is a low-temperature hybrid wafer bonding solution that allows wafers to be bonded with scalable fine pitch 3D electrical interconnect without requiring bond pressure. The technology is applicable to a wide range of semiconductor devices including MEMS, image sensors, RF front ends and stacked memory. DBI 3D interconnect can eliminate the need for through-silicon vias (TSVs) and reduce die size and cost while enabling pixel level interconnect for future generations of image sensors.

For more information on DBI technology and other advanced semiconductor packaging and interconnect solutions from Invensas, please visit www.invensas.com.

About Xperi Corporation

Xperi Corporation (Nasdaq: XPER) and its brands, DTS, FotoNation, HD Radio, Invensas and Tessera, are dedicated to creating innovative technology solutions that enable extraordinary experiences for people around the world. Xperi's solutions are licensed by hundreds of leading global partners and have shipped in billions of products in areas including premium audio, broadcast, automotive, computational imaging, computer vision, mobile computing and communications, memory, data storage, and 3D semiconductor interconnect and packaging. For more information, please call 408-321-6000 or visit www.xperi.com.

About Teledyne DALSA

Teledyne DALSA is an international technology leader in sensing, imaging, and specialized semiconductor fabrication. Our image sensing solutions span the spectrum from infrared through visible to X-ray; our MEMS foundry has earned a world-leading reputation. In addition, through our subsidiaries Teledyne Optech and Teledyne Caris, we deliver advanced 3D survey and geospatial information systems. Teledyne DALSA employs approximately 1,400 employees worldwide and is headquartered in Waterloo, Canada. For more information, visit www.teledynedalsa.com.

SOURCE: XPERI CORPORATION

XPER-I

View source version on businesswire.com: http://www.businesswire.com/news/home/20171214005411/en/

Xperi PR Agency:
The Brand Amp
Nicole Fait, +1 949-438-1104
nicolef@thebrandamp.com
or
Xperi PR:
Jordan Miller, +1 818-436-1082
jordan.miller@xperi.com
or
Xperi Investor Relations:
Geri Weinfeld, +1 818-436-1231
geri.weinfeld@xperi.com
or
Teledyne Media:
Geralyn Miller, +1 519-886-6000
geralyn.miller@teledyne.com

Source: Xperi Corporation

News Provided by Acquire Media